

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yuriy Reznik</td> <td>09/23/2011</td> </tr> <tr> <td>Onur C Hamsici</td> <td>09/23/2011</td> </tr> <tr> <td>Sundeepp Vaddadi</td> <td>09/27/2011</td> </tr> <tr> <td>John H Hong</td> <td>11/17/2011</td> </tr> <tr> <td>Chong U Lee</td> <td>11/17/2011</td> </tr> </tbody> </table>		Name	Execution Date	Yuriy Reznik	09/23/2011	Onur C Hamsici	09/23/2011	Sundeepp Vaddadi	09/27/2011	John H Hong	11/17/2011	Chong U Lee	11/17/2011
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>QUALCOMM Incorporated</td> </tr> <tr> <td>Street Address:</td> <td>5775 Morehouse Drive</td> </tr> <tr> <td>City:</td> <td>San Diego</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>92121-1714</td> </tr> </table>		Name:	QUALCOMM Incorporated	Street Address:	5775 Morehouse Drive	City:	San Diego	State/Country:	CALIFORNIA	Postal Code:	92121-1714		
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PROPERTY NUMBERS Total: 1													
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Application Number:	13229654												
CORRESPONDENCE DATA													
<p>Fax Number: (408)378-7770</p> <p>Phone: 408-378-7777</p> <p>Email: qualcomm_PAIR@svpatentgroup.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Silicon Valley Patent Group, Attn: QCM</p> <p>Address Line 1: 4010 Moorpark Avenue</p> <p>Address Line 2: Suite 210</p> <p>Address Line 4: San Jose, CALIFORNIA 95117</p>													
ATTORNEY DOCKET NUMBER:	Q111926USTC												
NAME OF SUBMITTER:	Thomas Chan												

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PATENT
REEL: 027276 FRAME: 0049

Total Attachments: 9

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ASSIGNMENT

WHEREAS, WE,

1. **Yuriy REZNIK**, a citizen of Ukraine, having a mailing address located at 8775 Costa Verde Blvd #319, San Diego, CA 92122, U.S.A., and a resident of San Diego, CA,
2. **Onur C. HAMSICI**, a citizen of Turkey, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., and a resident of La Jolla, CA,
3. **Sundeeep VADDADI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., and a resident of San Diego, CA,
4. **John H. HONG**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., and a resident of San Clemente, CA,
5. **Chong U. LEE**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **CODING OF FEATURE LOCATION INFORMATION** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/229,654** filed **September 9, 2011**, Qualcomm Reference No. **111926**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/522,171**, filed **August 10, 2010**, Qualcomm Reference No. **111926P1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part

applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

PATENT


QUALCOMM Ref. No. 111926

Page 3 of 3

Done at SAN DIEGO, on 9/23/11
LOCATION DATE


Yuriy REZNIK

Done at SAN DIEGO, on 9/23/11
LOCATION DATE


Onur C. HAMSICI

Done at _____, on _____
LOCATION DATE

Sundeep VADDADI

Done at _____, on _____
LOCATION DATE

John H. HONG

Done at _____, on _____
LOCATION DATE

Chong U. LEE

PATENT

REEL: 027276 FRAME: 0053

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WHEREAS, QUALCOMM Incorporated (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). **13/229,654** filed **September 9, 2011**, Qualcomm Reference No. **111926**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/522,171**, filed **August 10, 2010**, Qualcomm Reference No. **111926P1**, (and do hereby authorize **ASSIGNEE** and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part

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AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE

Yuriy REZNICK

Done at _____, on _____
LOCATION DATE

Onur C. HAMSICI

Done at SANDFIELD, on Sept-27-201
LOCATION DATE

V. Sundar
Sundeep VADDADI

Done at _____, on _____
LOCATION DATE

John H. HONG

Done at _____, on _____
LOCATION DATE

Chong U. LEE

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LOCATION DATE

Yuriy REZNICK

Done at _____, on _____
LOCATION DATE

Onur C. HAMSICI

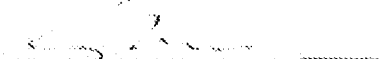
Done at _____, on _____
LOCATION DATE

Sundee VADDADI

Done at Sandiego, CA, on 11/17/11
LOCATION DATE


John H. HONG

Done at Sandiego, CA, on 11/17/2011
LOCATION DATE


Chong U. LEE